



Material Content Data Sheet



Sales Product Name		BSF035NE2LQ		Issued		29. August 2013			
MA#		MA001050858							
Package		MG-WDSON-2-3		Weight*		49.04 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.497	3.05	3.05	30531	30531	
leadframe	non noble metal	copper	7440-50-8	45.114	92.01	92.01	919943	919943	
leadfinish	non noble metal	nickel	7440-02-0	0.115	0.23		2339		
	noble metal	silver	7440-22-4	0.456	0.93	1.16	9302	11641	
plating	non noble metal	nickel	7440-02-0	0.077	0.16	0.16	1580	1580	
glue	plastics	epoxy resin	-	0.091	0.18		1846		
	noble metal	silver	7440-22-4	0.556	1.13	1.31	11337	13183	
solder	non noble metal	copper	7440-50-8	0.005	0.01		106		
	noble metal	silver	7440-22-4	0.031	0.06		638		
	non noble metal	tin	7440-31-5	1.006	2.05	2.12	20510	21254	
passivation	plastics	epoxy resin	-	0.092	0.19	0.19	1868	1868	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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